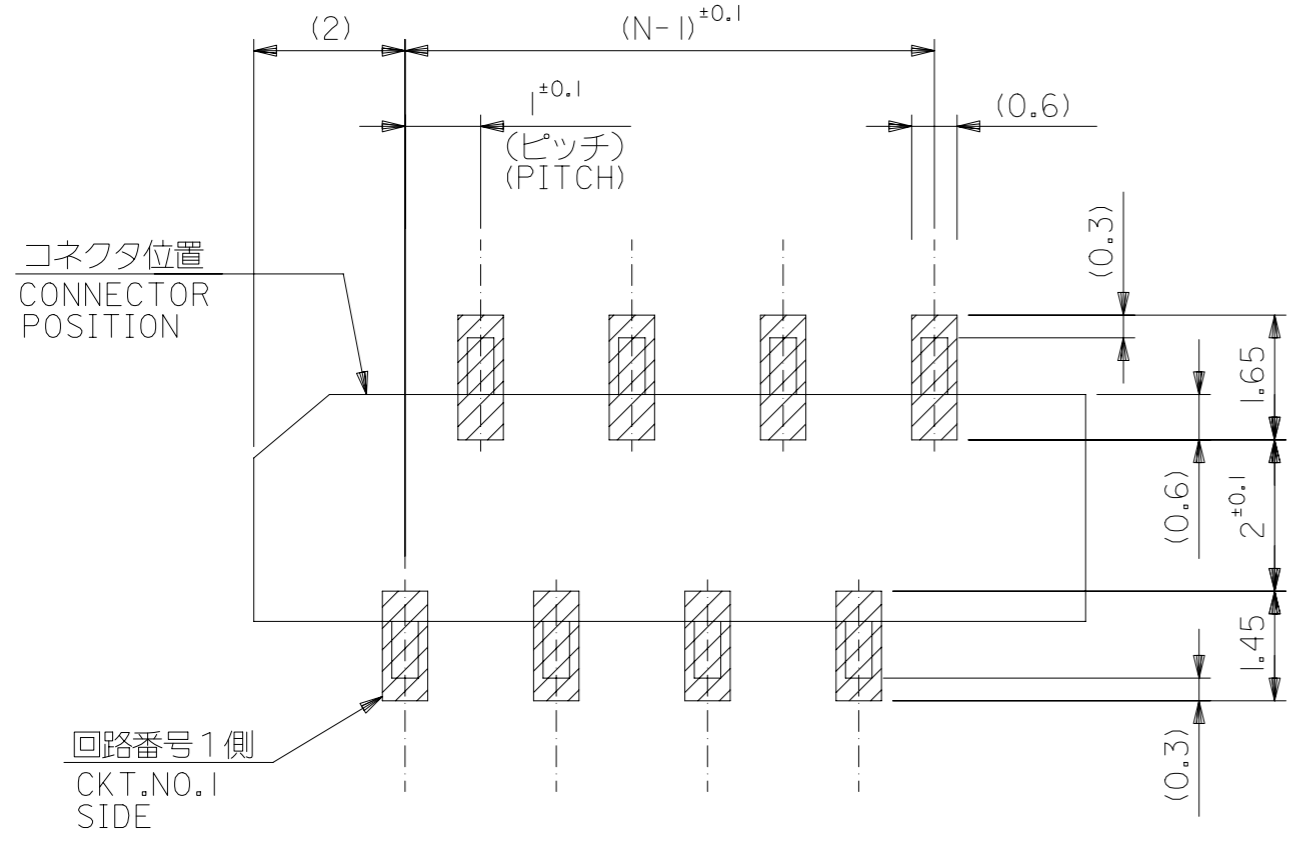


33	31.05	29	52808-3072	30
23	21.05	19	52808-2072	20
12	10.05	8	52808-0972	9
11	9.05	7	52808-0872	8
9	7.05	5	52808-0672	6
8	6.05	4	52808-0572	5
7	5.05	3	52808-0472	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	Ckt

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DIMENSION UNITS <b>mm</b>	SCALE <b>10:1</b>	CURRENT REV DESC: OBSOLETE PART NUMBER		
GENERAL TOLERANCES (UNLESS SPECIFIED)		<p>1.0 FFC CONN NON ZIF SMT ST ASSY</p> <p>PRODUCT CUSTOMER DRAWING</p>		
ANGULAR TOL	± 1.0 °			
4 PLACES	± 0.05			
3 PLACES	± 0.1			
2 PLACES	± 0.2			
1 PLACE	± 0.2	EC NO: 641324	2020/03/18	
0 PLACES	± 0.2	DRWN: AKUMAR19	2020/08/27	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHK'D: GGA	2020/08/27	
THIRD ANGLE PROJECTION		APPR: GGA	2020/08/27	
DRAWING		INITIAL REVISION:	DOCUMENT NUMBER	DOC TYPE
A3-SIZE		DRWN: MTAKAHASHI04	528081002	PSD
SERIES		APPR: TKUSUHARA01	000	B
MATERIAL NUMBER		2016/01/29		
CUSTOMER		2016/02/12		
SHEET NUMBER				
SEE TABLE				1 OF 3
GENERAL				



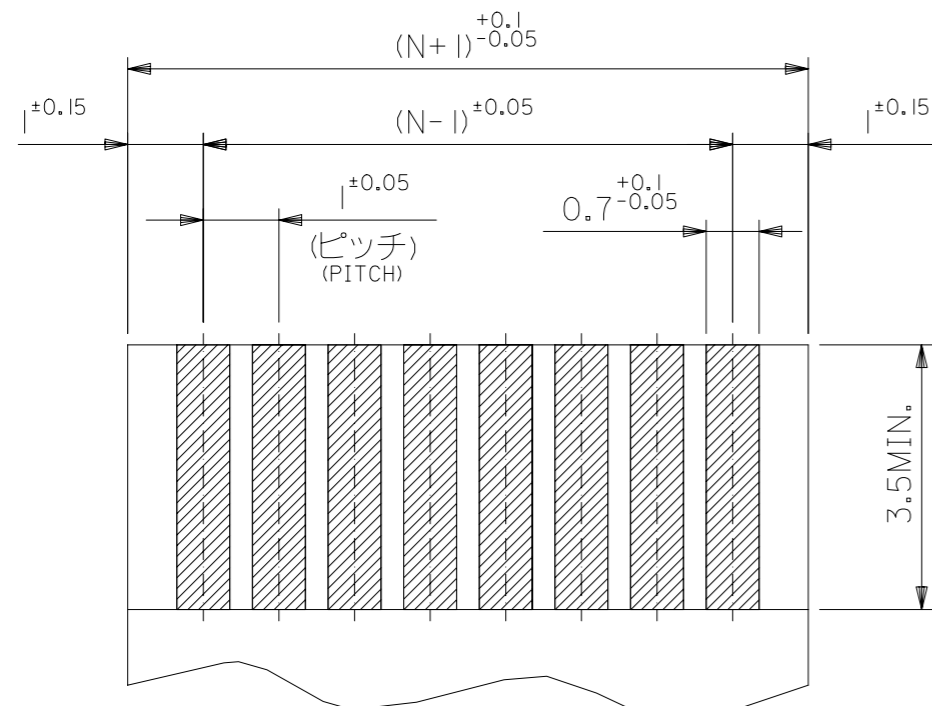
推奨基板レイアウト  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION  
 (マウント面)  
 (MOUNTING SIDE)

参考メタルマスク厚 : 120μm  
 参考メタルマスク開口率 : 100%  
 REFERENCE SCREEN THICKNESS : 120μm  
 REFERENCE SCREEN OPEN RATIO : 100%

注記 NOTES

1. 使用材料 MATERIAL  
 ハウジング : ポリフェニレンサルファイド(PPS) ナチュラル(白色) ガラス充填 UL94V-0  
 HOUSING POLY PHENYLENE SULFIDE NATURAL(WHITE) GLASS FILLED UL94V-0  
 ターミナル : リン青銅(t=0.25)  
 TERMINAL PHOSPHOR BRONZE (t=0.25)
2. めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部 : 金メッキ(0.1μm以上)  
 半田付部 : 錫メッキ(1.0μm以上)  
 下地 : ニッケルメッキ(1.0μm以上)  
 CONTACT PORTION : GOLD PLATING (0.1μm MIN)  
 SOLDERING PORTION : TIN PLATING (1.0μm MIN)  
 UNDER PLATING : NICKEL PLATING (1.0μm MIN)
3. 基準面 E からの溶ダテールの半田付け面のズレ量は、  
 上方向に0.1MAX、下方向に0.15MAXとする。  
 MISALIGNMENT OF SOLDER TAIL FROM E  
 UPPER DIRECTION 0.1 MAX , LOWER DIRECTION 0.15 MAX.
4. 偶数極に適用。  
 APPLY FOR EVEN CKT.
5. 本製品は 52808シリーズの金メッキ品です。  
 THIS PRODUCT IS Au PLATING OF 52808 SERIES.
6. ELV 及び RoHS適合品。  
 ELV AND RoHS COMPLIANT.

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DIMENSION UNITS	SCALE				
mm	1:1			1.0 FFC CONN NON ZIF SMT ST ASSY	
GENERAL TOLERANCES (UNLESS SPECIFIED)				PRODUCT CUSTOMER DRAWING	
ANGULAR TOL	± 1.0 °			DOCUMENT NUMBER	
4 PLACES	± 0.05	EC NO: 641324		528081002	
3 PLACES	± 0.1	DRWN: AKUMAR19 2020/03/18		DOC TYPE	
2 PLACES	± 0.2	CHK'D: GGA 2020/08/27		PSD	
1 PLACE	± 0.2	APPR: GGA 2020/08/27		DOC PART	
0 PLACES	± 0.2	INITIAL REVISION:		000	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRWN: MTAKAHASHI04 2016/01/29		REVISION	
THIRD ANGLE PROJECTION		APPR: TKUSUHARA01 2016/02/12		B	
DRAWING		SERIES		SHEET NUMBER	
A3-SIZE		52808		2 OF 3	
MATERIAL NUMBER		CUSTOMER			
SEE TABLE		GENERAL			



( 仕上り厚さ : 0.3±0.03 )  
 ( THICKNESS : 0.3±0.03 )  
適合金メッキFPC/FFC推奨寸法  
APPLICABLE GOLD FPC/FFC  
RECOMMENDED DIMENSION

**FPC/FFCについて**

打ち抜き方向は導体側から補強板側を推奨致します。  
 導体部については軟箔銅35μmまたは50μmを推奨致します。  
 接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。  
 FPC/FFCに規定された定格温度がFPC/FFC単体前提である場合が御座います。  
 コネクタと組み合わせての実使用において、接着層が劣化する等の信頼性を満足できないケースを回避する為、  
 実機での評価/確認をお願い致します。

**ABOUT FPC/FFC**

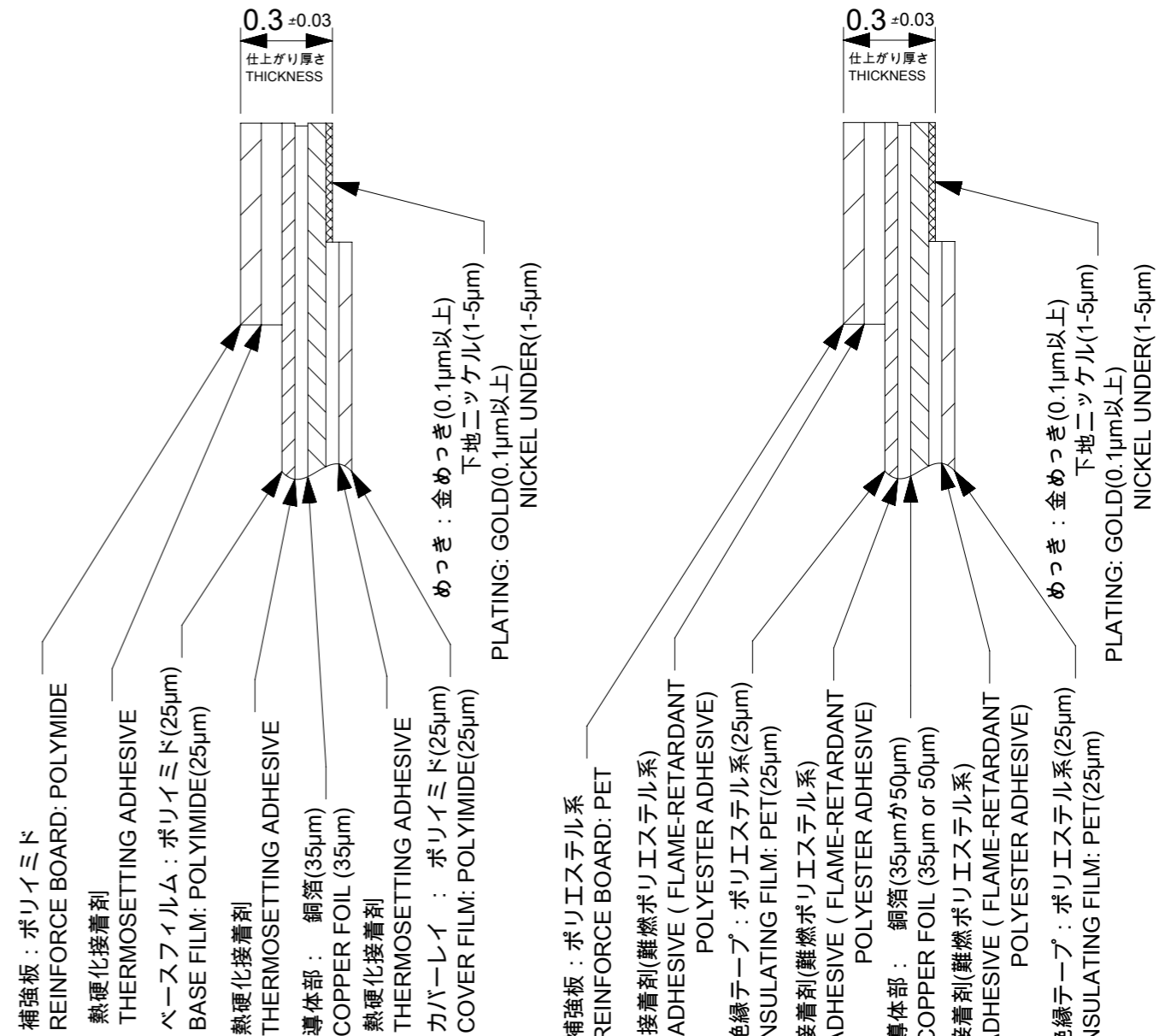
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE  
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL  
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS  
 A POSSIBILITY THAT EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY  
 THE HEAT RESISTANCE OF FFC IS ONLY FFC SPEC  
 TO PREVENT THE CASE THAT RELIABILITY CANNOT BE SATISFIED (THE ADHESIVE IS  
 DETERIORATED etc.) PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH  
 ACTUAL CONNECTER

**FPCについて**

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
 接着剤は熱硬化接着剤を推奨します。

**ABOUT FPC**

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE



**FPC構成推奨仕様**  
**STRUCTURE OF FPC**

**FFC構成推奨仕様**  
**STRUCTURE OF FFC**

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DIMENSION UNITS <b>mm</b>		SCALE <b>1:1</b>		CURRENT REV DESC: OBSOLETE PART NUMBER								
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ANGULAR TOL ± 1.0 °												
4 PLACES ± 0.05		EC NO: 641324		2020/03/18		<b>1.0 FFC CONN NON ZIF SMT ST ASSY</b>						
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1 PLACE ± 0.2		APPR: GGA		2020/08/27								
0 PLACES ± 0.2		INITIAL REVISION:		DOCUMENT NUMBER		DOC TYPE		DOC PART		REVISION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
				A3-SIZE		52808		528081002		PSD 000 B		3 OF 3
DOCUMENT STATUS		P1	RELEASE DATE		2020/08/27	08:37:42						